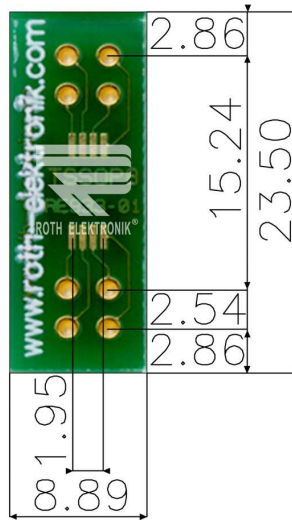


#### RE933-01

- Epoxy fibre-glass FR4 1.50 mm
  - Double-sided 35 µm Cu
  - Plated through holes (PTH)
  - Surface chem. Ni/Au with solder stop mask
  - Adaption circuit board for TSSOP 8
  - Pitch: 0.65 mm (173 mil)
  - Hole diameter 1.00 mm
  - Size 8.89 x 23.50 mm
- Module-No. Pitch mil Pin Size (mm)

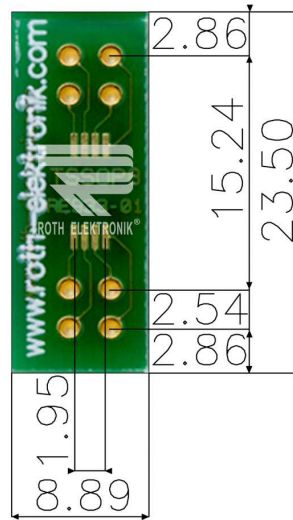
RE933-01 0.650 mm 22.5 8 4.400 (173 mil)



#### RE933-01

- Epoxydglashartgewebe FR4 1,50 mm
  - Zweiseitig 35 µm Cu
  - Durchkontaktiert (PTH)
  - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
  - Adaptionsplatine für TSSOP 8
  - Pitch: 0,65 mm (173 mil)
  - Lochdurchmesser 1,00 mm
  - Größe 8,89 x 23,50 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE933-01 0,650 mm 22,5 8 4,400 (173 mil)

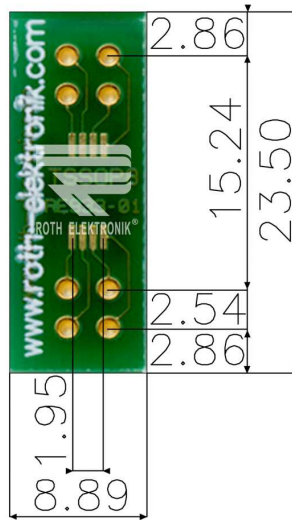


#### RE933-01

- Fibre de verre époxyde FR4 1,50 mm
- Double face 35 µm Cu
- Métallisation des trous (PTH)
- Surface avec Ni/Au chimique et un laque d'arrêt de soudure
- Platine d'adaptation pour TSSOP 8
- Pitch: 0,65 mm (173 mil)
- Perforation 1,00 mm Ø
- Dimensions 8,89 x 23,50 mm

Module-No. Pitch mil Pin Dimensions (mm)

RE933-01 0.650 mm 22.5 8 4.400 (173 mil)



#### RE933-01

- Fibra de vidrio epoxídica FR4 1,50 mm
  - Por dos lados 35 µm de Cu
  - Agujeros con contactos metalizados (PTH)
  - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
  - Adaptador para TSSOP 8
  - Pitch 0,65 mm (173 mil)
  - Diámetro de agujeros 1,00 mm
  - Tamaño 8,89 x 23,50 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)

RE933-01 0.650 mm 22.5 8 4.400 (173 mil)